TE Board Part Files

Most of the TE modules are available in different assembly options. Assembly option with different FPGA/SOC devices or other DDR sizes need an own board part file. In some cases also a PCB revision changes or a special carrier module combination needs a separate board part.

It's recommended to use the board part files only for this Vivado Version, for which it has been provided. Depending on the Schema Version of the XML-Files and Xilinx IP definitions, it is possible to use them with other Vivado versions, see Xilinx ug895.

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Naming Conventions and Version

This Naming Convention will be used for the most Vivado 2016.2 Board Part Files and newer one.

Board Part Files consists on a base folder, a version sub folder with three xml files and one picture:

- Every assembly option of a module/carrier series where FPGA-Typ (Size, Speed/Temperature Grade) is changed, gets a new base folder.
- · Every other assembly option or PCB-revision change, which has affects on the reference design settings, gets a new version sub folder.

Board Part Base Folder

Board Part Names of the base folder consists of max. three parts separated by underline character.

	Usage of the part of name	Example 1	Example 2	Example 3	Example 4	
Name of the PCB Series	Always	TE0726	TE0745	TE0720	TE0711	
FPGA Size	Optional		30		35	
FPGA Speed/Temperature Grade	Optional			1C	2C	

Board Part Version Folder

Version folder Name consists on a major and minor number separated by a dot (<major>.<minor>, example 1.0) Different Version folder means:

Major	 Changes on assembly option, which has effects on the reference design, for example DDR Size Boart Part for special Carrier/Module combination
Minor	Changes on PCB-Revision, which has effects on the reference design

Attention: Changes on the settings of the TE Board Part Files by itself are not under version control at the moment, like described in Xilinx ug895. XML file includes a comment header with the date of the last change of the selected file.

Location

Board Part Files will be delivered with our Reference Designs on our https://shop.trenz-electronic.de/Download/?path=Trenz_Electronic/<group>/<form factor>/<module_name>/Reference_Design/<vivado_version>/<design_name>.

Board Part Files are locate in the sub folder <design_name>/board_files/ of the downloadable Reference Design. For detailed information of the zip-file folder structure see: Project Delivery - Directory Structure.

This folder includes also a * board files.csv file with a list of all available board parts. This list is only used by TE-Scripts.

Select Correct Board Part Files



Since 2018.3 special "Module Selection Guide" is included into "_create_win_setup.cmd" and "_create_linux_setup.sh"

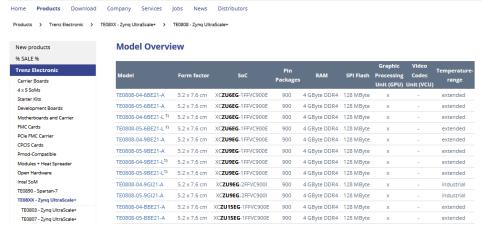
- Execute "_create_win_setup.cmd" or "_create_linux_setup.sh"
- Select "Module Selection Guide" (press "0" and Enter)
- **Follow instructions**
- Check <design name>/board files/<board series> board files.csv for available board part of the reference design:
 - The table shows all available board parts, which are delivered with the reference design
 - "ID" Unique ID for every board file in the project delivery
 - "PRODID" is the whole article name, latest reference design are available with all variants
 - "PARTNAME is the FPGA device setting of Vivado for the assembly variant
 - "BOARDNAME" is the corresponding board part file, which is used, files location is in "./board_files/<basename>/<XiI file id>/"
 - "SHORTNAME" is the name for the board part specific sub folders in the reference design
 - "ZYNQFLASHTYP" is the setting to configure the Flash via SDK
 - "FPGAFLASHTYP" is the setting to configure the Flash via Vivado (first part only), the second and third part are QSPI mode and memory size in
 - "PCB_REV" is supporte PCB Revision
 - -"DDR_SIZE" is DDR size if available
 - -"FLASH_SIZE" is Flash size if available -"EMMC_SIZE" is eMMC size if available

 - -"OTHERS" other HW notes
 - -"NOTES" additional notes
 - -"DESIGN" filter for the reference design usage

⊞ TE0000_board_files.cov ☑													
1 COV VERSIONS 1.4													
2 #Commenti-do not change matrix position or remove CSV VERSION;													
3	ID	PRODID	PARTHAME	BOARDHAME	. SECRITIANE	ZYMOFLASHTYP	. FPGAFLASHTYP	, ICB REV	.DOR SIZE	, FLASH SIZE	.EMMC SIZE	CTHERS	NOTES
- 4	#1	TE0000-E51	,xczu9eg-ffvc900-1-1-es1	treng.bin:te0000 esl:part0:1.0	esl 2gb	.gspi-x0-dual parallel	,mt25qu256-gapi-x0-dual parallel	,REV03 REV02		, 64365	, NA	, 33A	,"Not longer suppo
5	42	TE0808-ES1	.xozu9eg-ffvc900-1-1-esl	trenz.biz:te0808 esl tebf0808:part0:2.0	,esl_2gb	.ospi-x8-dual parallel	.mt25gu256-gspi-x8-dual parallel	, REV03 REV02	, 2GB	, 64MB	, 153 ₄	, NA	,"Not longer suppl
- 6	#3	TE0808-E52	.xczu9eg-ffvc900-1-1-es2	treng.bis:te0808_es2:part0:1.0	,es2_2gb	, gspi-x8-dual parallel	.mt25gu256-gspi-x8-dual parallel	.BEV04 BEV03	.26B	, 64MB	, NJA	.NA	. "Not longer suppo
	44	.TE0808-E52	.xczu9eg-ffvc900-1-1-ex2	treng.bix:te0805 es2 tebf0808:part0:2.0	,ex2 2gb	.gspi-x0-dual parallel	,mt25qu256-gapi-x0-dual parallel	REVO4 REVO3	.265	. 64005	. NA	, MA	,"Not longer suppo
8	45	,TE0808-2ES2	.xczu9eg-ffvc900-2-1-es2	trens.bis:te0808 2es2:part0:1.0	, 2es2 2db	.gspi-x0-dual parallel	.mt25gu256-gapi-x8-dual parallel	, REVO4 REVO3	, 2GB	, 64MB	, 103,	, NA	,"Not longer suppo
9	46	TE0808-2ES2	.xozu9eg-ffvo900-2-1-es2	trenz,bis:te0808 2es2 tebf0808:part0:2.0	, 2es2_2gb	.ospi-x8-dual parallel	.mt25gu256-gspi-x8-dual parallel	REV04 REV03	, 26B	, 64MB	, HJA	, NA	."Not longer suppl
	2	TE0808-04-09EG-1EA	xczu9eg-ffvc900-1-e	treng.biz:te0808 Seg le:part0:1.0	,9eg le 2gb	.gspi-x0-dual parallel	,mt25qu256-gapi-x8-dual parallel	REV04	, 2GB	, 64008	, NA	, NA	, NA
	0	,TE0000-04-09EG-1EA	,xczu9eg-ffvc900-1-e	.trenz.biz:te0000 Seg le tebf00003:part0:2.0	,9eg le 2gb	.gspi-x0-dual parallel	,mt25qu256-qapi-x0-dual parallel	, REVO 4	, 2GB	, 6480	, 103,	, NA	, 313.
	9	,TE0808-04-09EG-1EB	,xczu9eg-ffvc900-1-e	treng.bis:te0808_Seg_le:part0:3.0	,9eg_le_4gb	, gspi-x8-dual_parallel	,mt25qu256-qspi-x8-dual_parallel	, REVO 4	,4GB	, 64MB	, NA	, NA	, NA
	10	,TE0808-04-09EG-1EB	,xczu9eg-ffvc900-1-e	trent.bir:te0808 Seg le tebf0808:part0:4.0	, 9eg le 4gb	.gspi-x8-dual parallel	,mt25qu256-qspi-x8-dual parallel	,REVO4	,4GB	, 64MB	, NR	, NA	, NA
24	11	,TE0008-04-09EG-1ED	,xczu9eg-ffvc900-1-e	trent.biz:te0000 9eg le:part0:3.0	,9eg le 4gb	.gspi-x0-dual parallel	,mt25qu256-gapi-x0-dual parallel	, REVO 4	, 4GB	, 64365	, 103.	,"1 mm connectors"	*, NA
15	12	,TE0808-04-09EG-1ED	,xczu9eg-ffvc900-1-e	,treng.bis:te0808_Seg_le_tebf0808:part0:4.0	,9eg_le_4gb	.gspi-x8-dual_parallel	,mt25qu256-qspi-x8-dual_parallel	, REVO 4	,4GB	, 64MB	, NJA	,"1 mm connectors"	, NA
16	13	,TE0808-04-09EG-2IB	,xcsu9eg-ffvc900-2-1	trenz.biz:te0808_Seg_21:part0:3.0	,9eg_2i_4gb	.gspi-x8-dual parallel	,mt25qu256-qspi-x8-dual parallel	, REVO 4	,46B	, 64MB	, NR	, NA	, NA
	14	,TE0808-04-09EG-2IB	,xczu9eg-ffvc900-2-1	trent.bir:te0505 Seg 21 tebf0505:part0:4.0	,9eg 21 4gb	.gspi-x0-dual parallel	,mt25qu256-gapi-x5-dual parallel	,REVO4	, 4G5	, 64005	, MA	, NA	, 313.
	15	,TE0808-04-15EG-1EB	,xczulSeg-ffvc900-1-e	treng.bis:te0808_15eg_le:part0:3.0	,15eg_le_4gb	.gspi-x0-dual_parallel	,mt25qu256-qspi-x8-dual_parallel	, REVO 4	,4GB	, 64MB	, 10%	, NA	, NA
19			,xczulSeg-ffvc500-1-e	,trenz.bis:te0808_1Seg_le_tebf0808:part0:4.0	,15eg_le_4gb	, gspi-x8-dual_parallel	,mt25qu256-qspi-x8-dual_parallel	, REVO 4	,46B	, 64MB	, NR	, NA	, NA
20	17	,TE0808-04-09EG-1EE	,xczu9eg-ffvc900-1-e	trent.bir:te0808 Seg le:part0:3.0	,9eg le 4gb	.gspi-x0-dual parallel	,mt25qu512-qapi-x8-dual parallel	,REVO4	,4GB	,12898	, NR	, NA	, NA
			,xczu9eg-ffvc900-1-e		,9eg_le_4gb	.gspi-x0-dual_parallel	,mt25qu512-qspi-x0-dual_parallel	, REVO 4	,4GB	,12000	, 10%	, 37A	, 103.
	19	,TE0808-04-09EG-1EL	,xozu9eg-ffvo900-1-e	trenz.bis:te0808_Seg_le:part0:3.0	,9eg_le_4gb	, gspi-x8-dual_parallel	,mt25qu512-qspi-x8-dual_parallel	,REVO4	,4GB	,128MB	, HR	,"1 mm connectors"	*, NA
			,xczu9eg-ffvc900-1-e			.gspi-x8-dual_parallel	,mt25qu512-qgpi-x8-dual_parallel	,REV04	,4GB	,12898	, HA	,"1 mm connectors"	', NA
24	21	,TE0808-04-09EG-2IE	,xczu9eg-ffvc900-2-1	trenz.biz:te0808_9eg_21:part0:3.0	,9eg_21_4gb	.gspi-x0-dual_parallel	,mt25qu512-gapi-x0-dual_parallel	, REVO 4	, 4GB	,12000	, NA	, 37A	, 103.

- Check your order number and/or TE shop page to get module information of your PCB:
 - https://shop.trenz-electronic.de/en/Products/Trenz-Electronic/<device familie>/<TE module serie>

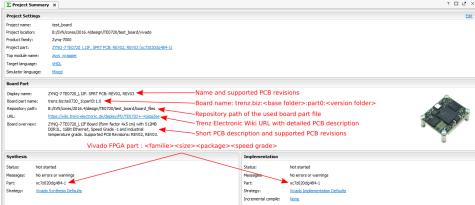
- "Model Overview" shows the basic difference between the assembly options, in the most cases different footprint compatible FPGAs or RAM size. Assembly options (like different connector) which has no affect on board parts settings, has no separate board part files.



- Select your board part file on design_basic_settings.cmd/sh:
 - Use unique name from CSV list (see 1.)
 - Unique names are ID or PRODID (in the most cases) or BOARDNAME or SHORTNAME
 - Revision number of the PRODID is the last one, which was available on last board part update. If there is no special board part for older revisions, this will be backward compatible. Please verify this on Vivado, see 4.

See Reference Design: Getting Started for more details.

- Create Vivado Project with vivado_create_project_guimode.cmd/sh
- Verify your board part selection on Vivado "Project Summary" tap:



Installation

See Vivado Board Part Installation and Project Delivery - QuickStart